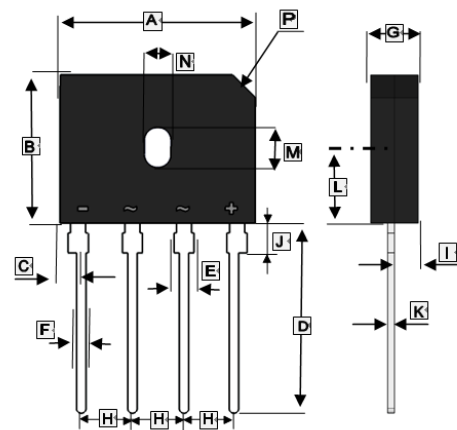


RoHS Compliant Product

FEATURES

- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique
- Plastic material has Underwriters Laboratory flammability classification 94V-0
- Mounting position: Any
- These are Halogen & Pb Free components

GBU



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	21.7	22.3	I	1.8	2.2
B	18.2	18.8	J	1.8	2.2
C	3.15	3.55	K	0.4	0.6
D	17.5	18.5	L	9.9	10.1
E	1.8	2.2	M	5.2	5.8
F	0.9	1.2	N	3.3	3.8
G	3.4	3.8	P	3 × 45°	
H	5	5.2			

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(Rating 25°C ambient temperature unless otherwise specified. Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, de-rate current by 20%.)

Parameter	Symbol	Part Number				Unit
		S8GBU20-C	S8GBU40-C	S8GBU60-C	S8GBU80-C	
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	200	400	600	800	V
Average Rectified Output Current @50HZ sine wave, R-load	$T_C=110^\circ\text{C}$ (with heat sink)	8				A
	$T_A=25^\circ\text{C}$ (without heat sink)	3.2				
Peak Forward Surge Current @ 50Hz sine wave, 1 cycle, $T_A=25^\circ\text{C}$	I_{FSM}	200				A
Maximum Peak Forward Voltage ³	V_{FM}	1				V
Peak Reverse Current ²	I_{RRM}	5				μA
I^2t Rating for Fusing @1ms ≤ t < 8.3ms, $T_J=25^\circ\text{C}$, Rating of per diode	I^2t	166				A^2s
Mounting Torque @ Recommend torque:5kg·cm	TOR	8				Kg · cm
Dielectric Strength ¹	Vdis	2				kV
Typical Thermal Resistance (with heat sink)	$R_{\theta JC}$	5				$^\circ\text{C}/\text{W}$
Typical Thermal Resistance(without heat sink)	$R_{\theta JA}$	23				$^\circ\text{C}/\text{W}$
Typical Thermal Resistance(without heat sink)	$R_{\theta JL}$	8				$^\circ\text{C}/\text{W}$
Operating and Storage temperature range	T_J, T_{STG}	150, -40~150				$^\circ\text{C}$

Notes :

1. Terminals to case · AC 1 minute
2. $V_{RM}=V_{RRM}$, Pulse measurement, Rating of per diode.
3. $I_{FM}=8.0\text{A}$, Pulse measurement, Rating of per diode

RATINGS AND CHARACTERISTIC CURVES

